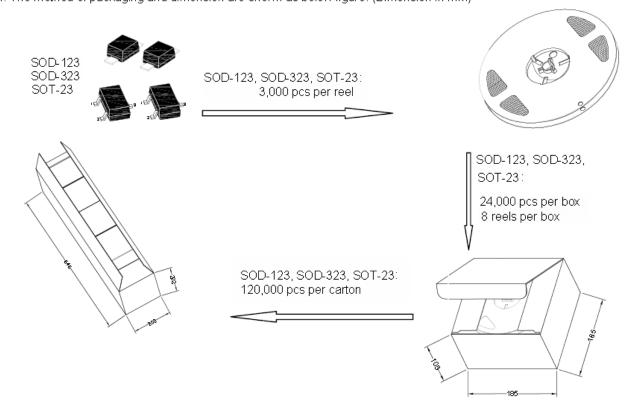
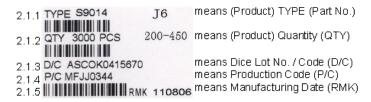
## **Packaging Specification for Surface Mounted Mold Diodes & Transistors**

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)



## 2. Label

2.1 The information of inner box label must be listed: (Description of a sample lable)



2.2 The information of carton label must be listed:

2.2.1 TYPE 2.2.2 QTY

Page 1 of 1 7/10/2011